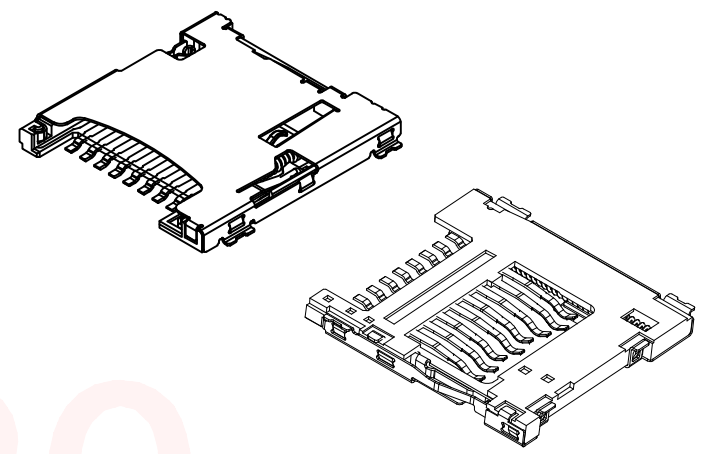
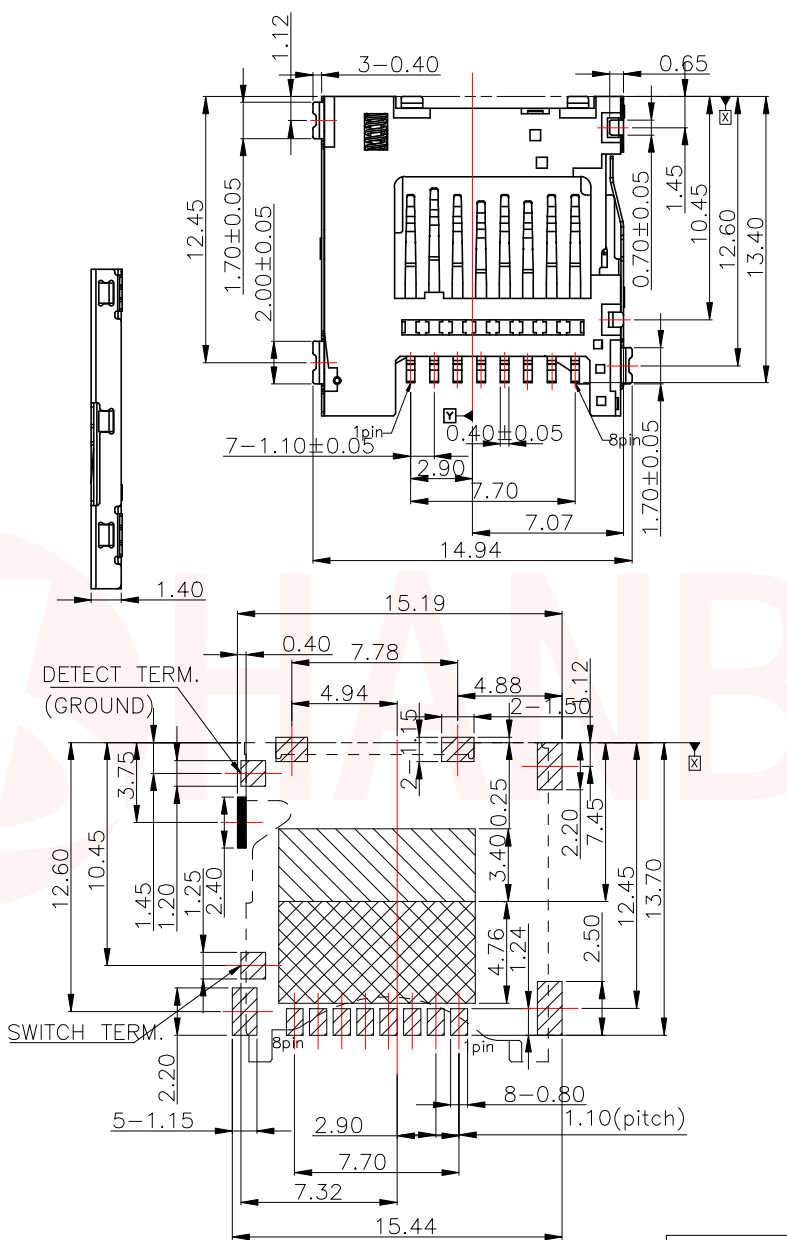
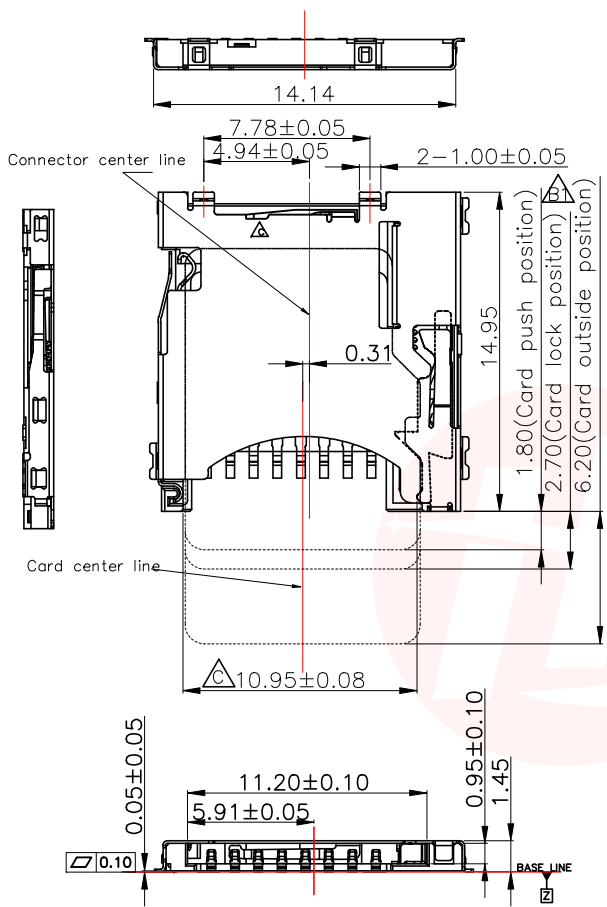




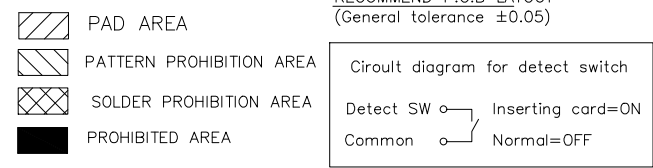
REV.	ECN NO OR DESCRIPTION	REVISED	DATE



Specification

- 1.MATERIAL:
- 1.1 Insulator:High Temperature Thermoplastic, (LCP, MG350), UL Black 94V-0.
 - 1.2 Contact: Phosphor Bronze(C5210R-H,T=0.15±0.03mm)
 - 1.3 Shell: SUS304-H T=0.12±0.03mm
- 2.Plating:
- 2.1 Contact: Plated 50u"min Ni Overall
Plated 1u"min Au Selective contact area
Plated 100u"min Sn over Ni on solder area
 - 2.2 Shell: Plated 50u"min Ni Overall
Plated 1u"min Au Selective Contact Area
- 3.Property:
- 3.1 Current Rating :0.5A AC/DC max.
 - 3.2 Voltage Rating :3.3V/5V(AC/DC)
 - 3.3 Contact Resistance:Contact Pin 100mΩ max.
 - 3.4 Insert/Pulling Force: 40N Max / 0.5~40N
 - 3.5 Smt Solder Temperature: Should Under 260°C
 - 3.6 Operation Temperature Range: -40~+85°C

PIN	T/F CARD
	microSD
8	P8 Dat1
7	P7 Dat0
6	P6 VSS
5	P5 CLK
4	P4 VDD
3	P3 CMD
2	P2 CD/Dat3
1	P1 Dat2



RECOMMEND P.C.B LAYOUT
(General tolerance ±0.05)

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS:	ANGLES:
X :±0.30	X :±2°
X.X :±0.20	X.X :±1°
X.XX :±0.05	

东莞市汉博电子科技有限公司
DONGGUAN HANBO TECHNOLOGY CO., LTD

TITLE	MICRO SD TF卡座1.45H SMT		
DWN	xiong	PART NO. TF-035-P8	
CHKD	lee	SCALE:1:1	UNIT: mm
APVD	wang	SIZE: A4	SHEET:10F 1
REV: A4			
CUSTOMER COPY			